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ATTY. DKT. 28951.2195

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 10/532,796

In re the Application of

Hideki TANAKA et al

Filed: April 25, 2005

For: PTC MATERIAL AND METHOD FOR PRODUCING SAME,
AND CIRCUIT PROTECTION COMPONENT USING SUCH
PTC MATERIAL AND METHOD FOR MANUFACTURING SAME

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
SUBMITTING SUBSTITUTE FORM PTO-1449**

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U.S. Patent and Trademark Office
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

Supplementing the Information Disclosure Statement filed April 25, 2005, submitted herewith is substitute Form PTO-1449 which is being submitted to correct errors in the listing of foreign patent documents. It is requested that the attached Form PTO-1449 be substituted for that originally filed on April 25, 2005.

Respectfully submitted,

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FORM 1449 (S&J Version) NOV 16 2005 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Docket No.: 28951.2195	
	Applicant: Hideki TANAKA al	
	Application No.:	
	Filing Date: April 25, 2005	
Examiner:		Group Art Unit:

U.S. PATENT DOCUMENTS

Examiner's Initials*	Document No.	Date MM/YYYY	Inventor	Class	Subclass	Filing Date If Appropriate

FOREIGN PATENT DOCUMENTS

Examiner's Initials*	Document No.	Date MM/YYYY	Country	Class	Subclass	Translation	
						Yes	No
	S55-78406	06/1980	Japan			Claims	
	05-345860	12/1993	Japan			Abstract	
	09-069416	03/1997	Japan			Abstract	
	2002-164201	6/2002	Japan			Abstract	

OTHER DOCUMENTS

Examiner's Initials*	Include author, title of article, title of item (book, journal, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.

Examiner's Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.